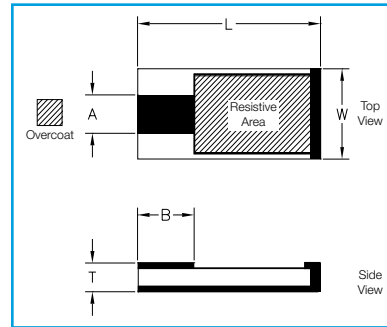


Leaded Chip Terminations

CT1 Style

GENERAL SPECIFICATIONS

- **Nominal Impedance:** 50 Ω
- **Resistive Tolerance:** ±5% standard, ±2% available
- **Operating Temp Range:** -55 to +150°C
- **Temperature Coefficient:** ±150 ppm/°C
- **Resistive Elements:** Tantalum, Thin Film Processed
- **Substrate Material:** Aluminum Nitride
- **Terminals:** Silver over Nickel
- **Lead-Free, RoHS Compliant**
- **Reliability:** MIL-PRF-55342
- **Tape and Reel Specifications:**

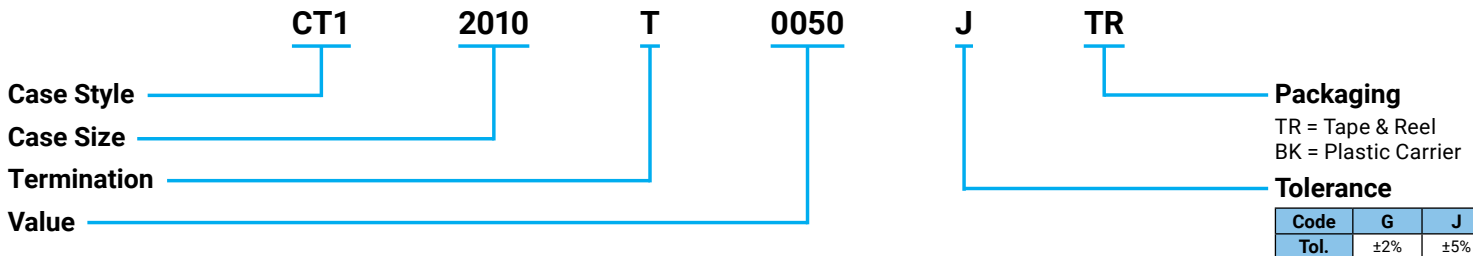


mm

Part Number	W ±.010	L ±.010	T ±.005	A ±.005	B (Typ.)	Frequency (GHz)	VSWR (Typ.)	Power Max* (Watts)
CT11020T0050J	.200	.100	.025	.034	.020	DC to 18.0	1.25:1	20W
CT12010T0050J	.100	.200	.040	.050	.060	DC to 4.0	1.20:1	30W
CT12525T0050J	.245	.245	.040	.090	.020	DC to 4.0	1.15:1	60W
CT12525T0050J01	.245	.245	.040	.050	.040	DC to 2.5	1.15:1	100W
CT12525T0050J02	.245	.245	.040	.090	.020	DC to 4.0	1.20:1	100W
CT12335T0050J	.350	.230	.040	.100	.030	DC to 4.0	1.15:1	100W
CT13725T0050J	.250	.375	.040	.090	.025	DC to 4.0	1.20:1	125W
CT13725T0050J01	.250	.375	.040	.050	.055	DC to 1.1	1.20:1	150W
CT13725T0050J02	.250	.375	.040	.090	.025	DC to 4.0	1.25:1	150W
CT13737T0050J	.370	.370	.040	.120	.025	DC to 2.0	1.25:1	150W
CT13737T0050J01	.370	.370	.040	.130	.065	DC to 1.0	1.20:1	250W

* Test Condition: Chip soldered to a large copper carrier whose surface is at 100°C; maximum rated power applied.
Specification: The resistance of the film shall change no more than <2% during and after a 1000-hr. Burn-in per MIL-PRF-55342.

HOW TO ORDER



POWER DERATING

